



MULTILAYER CERAMIC CAPACITORS

Ultra-small Series (6.3V to 50V)

01005 Size

NP0, X7R & X5R Dielectrics

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

01R5 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

2. FEATURES

- a. High capacitance in unit size.
- b. High precision dimensional tolerances.
- c. Suitable used in high-accuracy automatic mounting machine.

3. APPLICATIONS

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

4. HOW TO ORDER

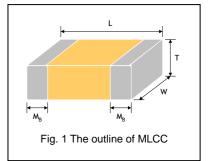
<u>01R5</u>	<u>N</u>	<u>100</u>	<u>C</u>	<u>160</u>	<u>C</u>	Ī
<u>Size</u>	<u>Dielectric</u>	Capacitance	<u>Tolerance</u>	Rated voltage	Termination	Packaging
01R5 = 01005 (0402)	B =X7R X =X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF 100=10x10 ⁰	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2% J=±5% K=±10% M=±20%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 6R3=6.3 VDC 100=10 VDC 160=16 VDC 250=25 VDC	C =Cu/Ni/Sn	T=7" reeled
		=10pF	Chholog	500=50 VDC		

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5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Syr	nbol	M _B (mm)	
01R5 (0402)	0.40±0.02	0.20±0.02	0.20±0.02	V	0.10±0.03	
* Reflow soldering only						

Reflow soldering only.



6. GENERAL ELECTRICAL DATA

Size	01R5			
Dielectric	NP0	X7R	X5R	
Capacitance* 0.2pF to 100pF		100pF to 1000pF	1000pF to 0.1µF	
	Cap≤5pF: A (±0.05pF), B (±0.1pF), C (±0.25pF) 5pF <cap<10pf: C (±0.25pF), D (±0.5pF) Cap≥10pF: F (±1%), G (±2%), J (±5%)</cap<10pf: 	K (±10%), M (±20%)		
Rated voltage (WVDC)	16V, 25V, 50V	_10V 213	6.3V, 10V	
DF / Q ^{#1}	Cap<30pF, Q≥400+20C Cap≥30pF, Q≥1000	≤5 %	≤10 %	
Insulation resistance at Ur	≥10GΩ or RxC≥500Ω*F	whichever is less	RxC≥50Ω*F	
Operating temperature	-55 to +125℃	-55 to +125℃	-55 to +85℃	
Capacitance change	±30ppm	±15%		
Termination	Ni/Sn (lead-free termination)			

NP0: Apply 0.5~5Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature. X5R: Apply 0.5±0.2Vrms or 1.0±0.2Vrms^{#1}, 1.0kHz±10%, at the condition of 25°C ambient temp erature.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

#1: Please refer to "RELIABILITY TEST CONDITIONS AND REQUIREMENTS" for detail







7. CAPACITANCE RANGE

	SIZE	01R5		
	DIELECTRIC		NP0	
RAT	ED VOLTAGE (VDC)	16	25	50
	0.2pF (0R2)	V	V	V
	0.3pF (0R3)	V	V	V
	0.4pF (0R4)		V	V
	0.5pF (0R5)	V	V	V
	1.0pF (1R0)	V	V	V
	1.5pF (1R5)	V	V	V
	2.0pF (2R0)	V	V	V
	3.0pF (3R0)		V	V
	4.0pF (4R0)	V	V	V
	5.0pF (5R0)	V	V	V
_	6.0pF (6R0)	V	V	V
Capacitance	7.0pF (7R0)	V	V	V
tar	8.0pF (8R0)	V	V	V
aci	9.0pF (9R0)	V	V	V
ap	10pF (100)	V	V	V
ပ	12pF (120)	V	V	V
	15pF (150)	V	V	V
	18pF (180)	V	V	V
	22pF (220)	V	V	V
	27pF (270)	V	V	V
	33pF (330)	<u> </u>	V	V
	39pF (390)	V	V	VE
	47pF (470)	<u> </u>	V	No. ()
	56pF (560)	<u> </u>	V	V
	68pF (680)	<u> </u>	V	
	82pF (820)	<u> </u>	VAN	N N
	100pF (101)	V	VTTL	

SIZE		01R5
	DIELECTRIC	X7R
RA	TED VOLTAGE (VDC)	10
	100pF (101)	V
Capacitance	150pF (151)	V
itaı	220pF (221)	V
oac	330pF (331)	V
Cap	470pF (471)	V
	1,000pF (102)	V

	SIZE	01	R5
	DIELECTRIC	X5R	
RA	TED VOLTAGE (VDC)	6.3	10
	1,000pF (102)	V	V
	1,500pF (152)		V
	2,200pF (222)		V
	3,300pF (332)		V
Capacitance	4,700pF (472)		V
tan	6,800pF (682)		V
gci	0.010µF (103)	V	V
api	0.015µF (153)		
Ü	0.022µF (223)	V	
	0.033µF (333)	V	
	0.047µF (473)	V	
	0.068µF (683)		
	0.10µF (104)	V	

1. The letter in cell is expressed the symbol of product thickness.

 For more information about products with special capacitance or other data, please contact WTC local representative.

8. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Sumh	Paper tape		r tape
Size	Thickness (mm)/Symbol		7" reel	13" reel
01R5 (0402)	0.20±0.02	V	20,000	-

Unit: pieces



9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem	Test Condition	Requirements	
1.	Visual and Mechanical		* No remarkable defect. * Dimensions to conform to individual specification sheet.	
2.	Capacitance	Class I: NP0	* Shall not exceed the limits given in the detailed spec.	
3.	Q/ D.F. (Dissipation Factor)	Cap≤1000pF, 0.5~5Vrms, 1MHz±10% Cap>1000pF, 1.0±0.2Vrms, 1KHz±10% Class II: , X7R & X5R(≥10V) 1.0±0.2Vrms, 1KHz±10% Class II: , X5R(≤6.3V) 0.5±0.2Vrms, 1kHz±10% *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp.	* NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C X7R: ≤5.0 % X5R: ≤10 %	
4.	Dielectric Strength	 * To apply voltage (≤100V) 250%. * Duration: 1 to 5 sec. * Charge and discharge current less than 50mA. 	* No evidence of damage or flash over during test.	
5.	Insulation Resistance	To apply rated voltage for max. 120 sec.	* NP0, X7R: ≥10GΩ or RxC≥500Ω-F whichever is smaller. X5R: RxC≥50Ω-F	
6.	Temperature	With no electrical load.		
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change	
		NPO -55~125°C at 25°C	NPO Within ±30ppm/℃	
		X7R -55~125°C at 25°C	X7R Within ±15%	
		[*] Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24± 2 hrs at room temp. *Measurement voltage for Class II Cap≤0.01μF: 0.5V Cap>0.01μF: 0.2V		
7.	Adhesive Strength of Termination	* Pressurizing force : 1N	* No remarkable damage or removal of the terminations.	
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.	
	Resistance	 * Total amplitude: 1.5mm * Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24± 2 hrs at room temp. * Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. 	* No remarkable damage. * Cap change and Q/D.F.: To meet initial spec.	
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.	
10.	* Dipping time: 2±0.5 sec. Bending Test * The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second un the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs.		 * No remarkable damage. * Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% X5R: within ±25.0% (This capacitance change means the change of capacitance unde specified flexure of substrate from the capacitance measured before the test.) 	



No.	ltem	Test Condition		Requirements	
11.	Resistance to	* Solder temperature: 260±5℃		* No remarkable damage.	
	Soldering Heat	 Dipping time: 10±1 sec Preheating: 120 to 150°C for 1 minute before i capacitor in a eutectic solder. 	mme rse the	* Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5%	
		* Before initial measurement (Class II only): To at 150°C for 1hr then set for 24±2 hrs at room te	emp.	X5R: within $\pm 15.0\%$ Q/D.F., I.R. and dielectric strength: To meet initial requirements.	
12	Temperature	* Cap. / DF(Q) / I.R. Measurement to be made a at 150°C for 1hr then set for 24±2 hrs at room te * Conduct the five cycles according to the temp.	emp.	* 25% max. leaching on each edge.	
12.	-	time.	eratures and	* Cap change:	
	-		me (min.)	NP0: within ±2.5% or ±0.25pF whichever is larger.	
		1 Min. operating temp. +0/-3 30)±3	X7R: within ±7.5%	
		2 Room temp. 2~	.3	X5R: within $\pm 15.0\%$	
		3 Max. operating temp. +3/-0 30)±3	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.	
		4 Room temp. 2~	.3		
		* Before initial measurement (Class II only): To at 150°C for 1hr then set for 24±2 hrs at room te * Cap. / DF(Q) / I.R. Measurement to be made a	emp.		
10		at 150℃ for 1hr then set for 24±2 hrs at room te	emp.		
13.	Humidity (Steady State)	* Test temp.: 40±2℃ * Humidity: 90~95% RH		* No remarkable damage. * Cap change:	
	(Sieady Sidle)	* Test time: 500+24/-0hrs.		NP0: within ±5.0% or ±0.5pF whichever is larger.	
		* Before initial measurement (Class II only): To	apply de-aging		
		at 150° for 1hr then set for 24 ± 2 hrs at room temp.		X5R: within ±25.0%	
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging		* Q/D.F. value:	
		at 150℃ for 1hr then set for 24±2 hrs at room te	肥又万大	NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C	
		two is the		Cap<10pF; Q≥200+10C X7R: ≤7.5%	
		TTYLE HE		X5R:≤20%	
				* I.R.:	
		PSA		NP0, X7R: ≥1GΩ or RxC≥50Ω-F whichever is smaller.	
14	Humidity Load	* Test temp.: 40±2°C	SYSTEM ALL	X5R: RxC≥10Ω-F. * No remarkable damage.	
14.	(Damp Heat)	* Humidity: 90~95%RH		* Cap change:	
	(* Test time: 500+24/-0 hrs.		NP0: within $\pm 7.5\%$ or ± 0.75 pF whichever is larger.	
		* To apply voltage : rated voltage.		X7R: within ±15.0%	
		* Before initial measurement (Class II only): To		X5R: within ±25.0%	
		at 150°C for 1hr then set for 24 \pm 2 hrs at room te		* Q/D.F. value:	
		* Cap. / DF(Q) / I.R. Measurement to be made a at 150°C for 1hr then set for 24±2 hrs at room t		NP0: Cap≥30pF, Q≥200; Cap<30pF; Q≥100+10/3C \X7R: ≤7.5%	
			OGY CORPOR	X5R: ≤20%	
			Con Com o.	* I.R.:	
				NP0, X7R: ≥500MΩ or RxC≥25Ω-F whichever is smaller. X5R: RxC≥5Ω-F.	
15.	High	* Test temp.:			
	Temperature	NP0, X7R: 125±3℃			
	Load (Endurance)	X5R: 85±3℃ * To apply voltage:			
	(Endurance)	(1) NP0, X7R : 200% of rated voltage			
		(2) X5R: 10V : 150 % of rated voltage		* No remarkable damage.	
		6.3V : 100 % of rated voltage		* Cap change:	
		* Test time: 1000+24/-0 hrs.		NP0: within ±3.0% or ±0.3pF whichever is larger.	
		* Before initial measurement (Class II only): To a at 150°C for 1hr then set for 24±2 hrs at room te		X7R: within ±12.5% X5R: within ±25.0%	
		* Cap. / DF(Q) / I.R. Measurement to be made a		* Q/D F value:	
		150°C for 1hr then set for 24 ± 2 hrs at room tem	ıp.	NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C	
		** De-rating conditions:		Cap<10pF; Q≥200+10C	
				X7R: ≤7.5%	
		100	iet 5°C	X5R: ≤20%	
		Produ	iet i5°C	* I.R.: NP0_X7P: >1C0 or PxC>500 E whichover is smaller	
		g oo	rct °C	NP0, X7R: ≥1GΩ or RxC≥50Ω-F whichever is smaller. X5R: RxC≥10Ω-F.	
			:		
		40 40 40 40 40 40 40 40 40 40			

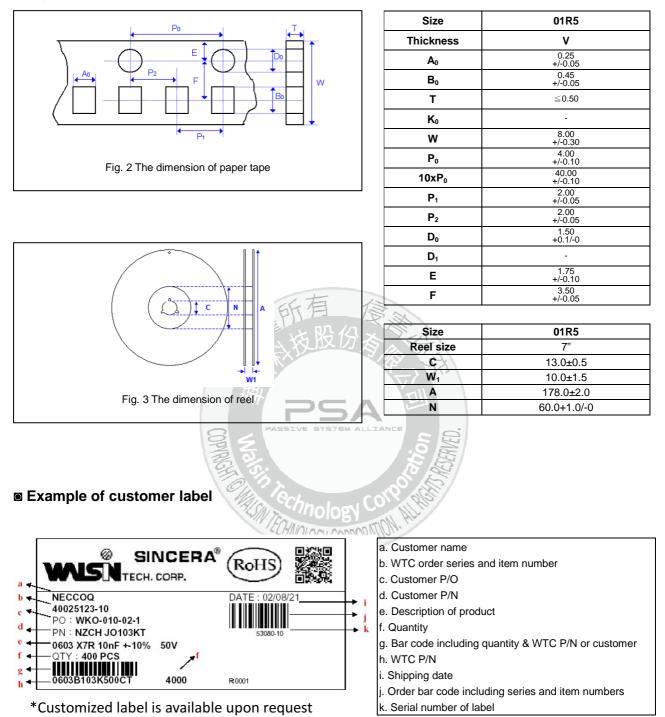
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ASC_Ultra Small_(01R5)_026G_AS

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APPENDIXES

Tape & reel dimensions

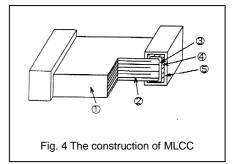


Approval Sheet

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Constructions

No.	Name		NP0	X7R, X5R
1	Ceramic material		CaZrO ₃ based	BaTiO₃ based
2	Inner electrode		Ni	
3		Inner layer	С	u
4	Termination	Middle layer	Ni	
5		Outer layer	Sn (I	Matt)



Approval Sheet

Storage and handling conditions

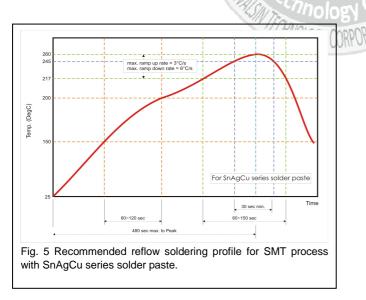
- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions; MSL Level 1.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Kamaya:

01R5B102K100CT 01R5X104K6R3CT

Walsin:

<u>01R5N0R5B160CT</u> <u>01R5N150J160CT</u> <u>01R5N120J160CT</u> <u>01R5N2R0C160CT</u> <u>01R5N3R0C160CT</u> <u>01R5N4R0C160CT</u> <u>01R5N5R0C160CT</u> <u>01R5N7R0D160CT</u>